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Class K equivalent die up-screening

MIL-PRF-38534 Class K Equivalent Up-screening Rev L		
Screening Requirements		
Test	Quantity (Accept Number of Failures)	Specification and Test Method
Subgroup 1: Electrical Test	100%	
Subgroup 2: Visual Inspection	100%	MIL-STD-883: 2010 MIL-STD-750: 2069, 2070, 2072, 2073
Subgroup 3A: Internal/Die Visual Inspection	10 (0)	MIL-STD-883: 2010 MIL-STD-750: 2069, 2070, 2072, 2073
Subgroup 3B: Sample Assembly	10	
Subgroup 4A: Electrical Test as per Datasheet: DC Test @25°C (DC1)	10 devices per wafer (0)	
Subgroup 4B: Temperature Cycling	10 devices per wafer (0)	MIL-STD-883:1010-C 20 Cycles
Subgroup 4C: Mechanical Shock or Constant Acceleration	10 devices per wafer (0)	MIL-STD-750: 2002 or 2001 B, Y1 direction or 5000 g's Y1 Direction
Subgroup 4D: Electrical Test as per Datasheet: DC Test @ 25°C / DC Test @ 125°C /DC Test @-55°C/ (DC2-DC4)	10 devices per wafer (0)	
Subgroup 4E: HTRB	10 devices per wafer (0)	MIL-STD-750 240 Hours, TA Minimum 125°C
Subgroup 4F: Electrical Test as per Datasheet: DC Test @ 25°C / DC Test @ 125°C / DC Test @-55°C/ (DC5-DC7)	10 devices per wafer (0)	
Subgroup 4G: Steady State Life	10 devices per wafer (0)	MIL-STD-750 1000 Hours, TJ Minimum 125°C
Subgroup 4H: Electrical Test as per Datasheet: DC Test @ 25°C / DC Test @ 125°C / DC Test @-55°C/ (DC8-DC10)	10 devices per wafer (0)	
Subgroup 5: Wire Pull	10 Wires (0) or 20 Wires (1)	MIL-STD-883: 2011-D 1 Hour 300C Pre-Test Bake (Bimetallic Bonds)
Subgroup 6: SEM	Per Mil Standard	MIL-STD-750: 2077

Note: Devices supplied will be to the test flow illustrated above. Any changes to the flow must be agreed upon in writing by the customer and Central Semiconductor Corp.